

RoHS+Halogen Compliant

SPECIFICATION (Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31B223KGHNNNE
- Description : C/
- CAP, 22nF, 500V, ±10%, X7R, 1206

A. Samsung Part Number

		<u>CL</u> ①	<mark>31</mark> ②	B 223 3 4	<u>K</u> 5	<u>G</u> 6	<u>н</u> Т	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<u>Е</u> 11			
1	Series	Samsung Multi-layer Ceramic Capacitor												
2	Size	1206 (inch c	ode)	L:	3.2	± 0.2		mm		W:	1.6	± 0.2	mm	
3	Dielectric	X7R			8	Inner electrode			Ni					
4	Capacitance	22 nF				Tern	ninat	ion			Cu			
5	Capacitance	±10 %				Plati	ng				Sn 10	00%	(Pb Free)	
	tolerance				9	Prod	luct				Norm	nal		
6	Rated Voltage	500 V			10	Spec	cial				Rese	rved for	future use	
\bigcirc	Thickness	1.6 ± 0.2	mm		1	Pack	agir	g			Embo	ossed T	ype, 7" reel	

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1ktz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.	1					
Insulation	10,000Mohm or 500Mohm· <i>µ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	150% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R	·					
Characteristics	(From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120 ℃ for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition						
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm						
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)						
		2hours \times 3 direction (x, y, z)						
Moisture	Capacitance change : within ±12.5%	With rated voltage						
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs						
	IR : 500Mohm or 25Mohm · <i>μ</i> F Whichever is Smaller							
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage						
Resistance	Tan δ : 0.05 max	Max. operating temperature						
	IR : 1000Mohm or 50Mohm $\cdot \mu F$							
Whichever is Smaller		1000+48/-0hrs						
Temperature	Capacitance change : within ±7.5%	1 cycle condition						
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C						
		\rightarrow Max. operating temperature \rightarrow 25 °C						
		5 cycle test						

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.